

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				ATTY DOCKET NO CVI-0006		SERIAL NO 10 091.055	
				APPLICANT(S) Ralph S. Jameson et al			
				FILING DATE 3/4/02		GROUP	

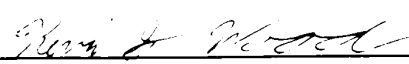
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)	
KSW	5,482,585	1/9/96	Ota et al	385	49		
KSW	5,497,438	3/5/96	Ishikawa et al	385	38		
KSW	5,499,309	3/12/96	Kozuka et al	385	38		
KSW	5,559,915	9/24/96	DeVeau	385	49		
KSW	5,656,120	8/12/97	Ota et al	385	49		
KSW	5,708,741	1/13/98	DeVeau	385	49		
KSW	5,715,341	2/3/98	Osugi et al	385	50		
KSW	5,970,192	10/19/99	Osugi et al	385	49		
KSW	5,790,731	8/4/98	DeVeau	385	49		
KSW	5,946,099	8/31/99	Ota et al	356	614		
KSW	6,027,253	8/22/00	Ota et al	385	83		

FOREIGN PATENT DOCUMENTS								
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION		
						YES	NO	
KSW	EP0627641B1	24.02.1999	Europe	G02B	6/42			
KSW	JP8179171	9/28/1994	Japan	G02B	6/42			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)			
KSW		Web Page: Rogers Corporation: Engineered Moldable Composites/Moldable Composites Division/"Reflection TM White Epoxy" (No Date)	
KSW		Web Page: ROGERS: Engineered Moldable Composites REFLECTION TM White Epoxy Application Report "Rogers REFLECTION TM White Epoxy Enables Smaller Electronic Packages" (No Date)	

EXAMINER <i>Norm J. [Signature]</i>	DATE CONSIDERED <i>7/17/02</i>
--	-----------------------------------

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				ATTY DOCKET NO. CVI-0006		SERIAL NO. 10/091,055	
				APPLICANT(S) Ralph S. Jameson et al			
				FILING DATE 3/4/02		GROUP	
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
KSW		6,103,344	8/15/00	Ota et al	385	65	
KSW		6,160,937	12/12/00	Fukuyama et al	385	52	
KSW		6,195,495 B1	2/27/01	Ota et al	385	137	
KSW		6,215,944 B1	4/10/01	Ota et al	385	137	
KSW		6,215,945 B1	4/10/01	Fukuyama et al	385	137	
KSW		6,231,244 B1	5/15/01	Fukuyama et al	385	76	
KSW		5,566,262	10/15/96	Yamane et al	385	33	
KSW		5,700,987	12/23/97	Basavanhally	219	56.1	
KSW		5,930,600	7/27/99	Seelert et al	438	118	
KSW		6,033,515	3/7/00	Walters et al	385	51	
KSW		6,146,025	11/14/00	Abbink et al	385	88	
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
EXAMINER				DATE CONSIDERED			
				7/17/03			
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				ATTY DOCKET NO. CVI-0006		SERIAL NO. 10/091.055	
				APPLICANT(S) Ralph S. Jameson et al			
				FILING DATE 3/4/02		GROUP	

U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>ASW</i>		6.181.864 B1	1/30/01	Jang et al	<i>385</i>	<i>137</i>	
<i>ASW</i>		6.243.518	6/5/01	Lee et al	<i>385</i>	<i>59</i>	
<i>ASW</i>		6.304.708 B1	10/16/01	Fukuyama et al	<i>385</i>	<i>137</i>	
<i>ASW</i>		5.339.876	8/23/94	Mattern	<i>141</i>	<i>51</i>	

FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>			

EXAMINER <i>Keun & Wood</i>	DATE CONSIDERED <i>7/17/03</i>
------------------------------------	-----------------------------------

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.